Step 1: Raw Material (Cu Panel)

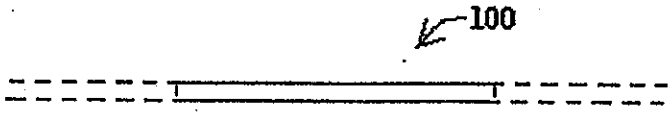

FIG. 1A

Step 2: Etch Resist Coating

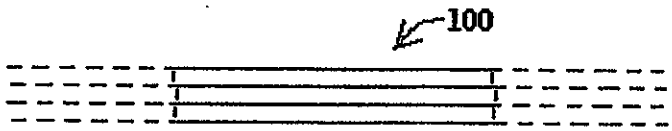

FIG. 1B

Step 3: UV Exposure With Phototool

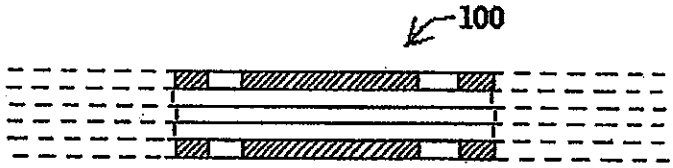

FIG. 1C

Step 4: Developing

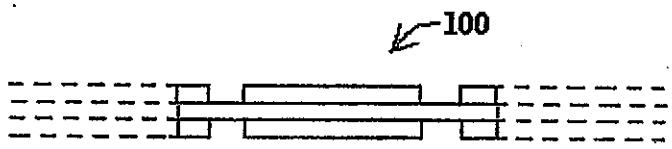

FIG. 1D

Step 5: Immersion Etching and Stripping

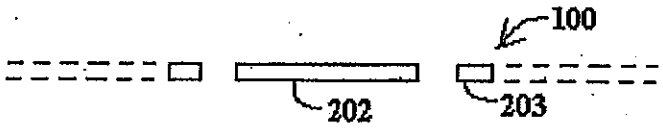

FIG. 1E

Step 6: Selective Plating with Ag And Chemical Dipping

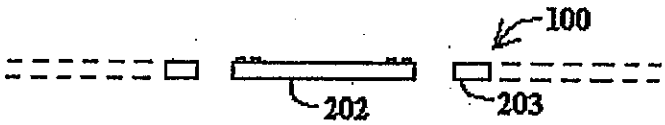

FIG. 1F

Step 7: Die Attach, Wire Bonding, Molding And Singulation or Saw Punching

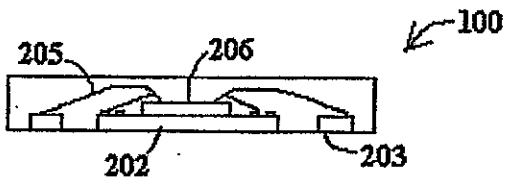

FIG. 1G

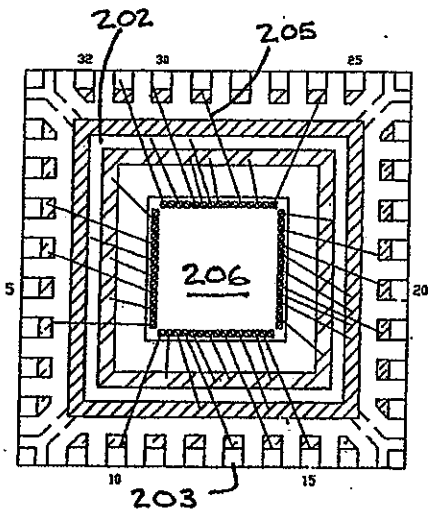
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FIG. 2A

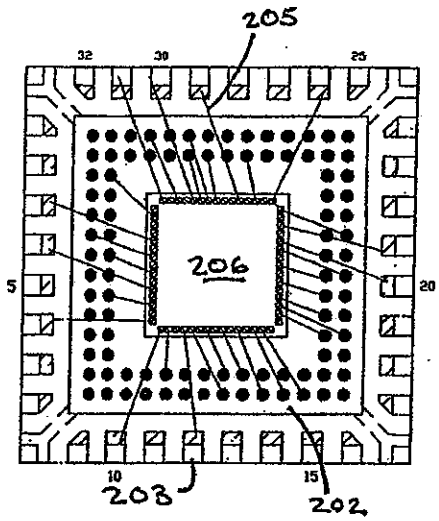
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FIG 2B